

BGA Heat Sink - High Performance Device Specific - NXP



ATS Part#: **ATS-59001-C1-R0**
 Description: 28.00 x 45.00 x 11.00 mm BGA Heat Sink - High Performance Device Specific - NXP
 Heat Sink Type: NXP
 Heat Sink Attachment: **maxiGRIP**
 Equivalent Part Number: **ATS-59001-C2-R0 Discontinued**

**Image above is for illustration purpose only.*

Features & Benefits

- Designed for flip-chip processors such as NXP MPCs
- **maxiGRIP™** attachment applies steady, even pressure to the component and does not require holes in the PCB
- Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance

| AIR VELOCITY | | @200 LFM 1.0 M/S | @300 LFM 1.5 M/S | @400 LFM 2.0 M/S | @500 LFM 2.5 M/S | @600 LFM 3.0 M/S | @700 LFM 3.5 M/S | @800 LFM 4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 4.5 °C/W | 3.6 °C/W | 3.2 °C/W | 2.9 °C/W | 2.7 °C/W | 2.5 °C/W | 2.4 °C/W |
| | Ducted Flow | 3 | N/A | N/A | N/A | N/A | N/A | N/A |

Product Detail

| Schematic Image | Dimension A | Dimension B | Dimension C | Dimension D | TIM | Finish |
|--|-------------|-------------|-------------|-------------|------|----------------|
| <p><i>*Image above is for illustration purpose only.</i></p> | 28.00 mm | 45.00 mm | 11.00 mm | 59 mm | T766 | BLACK-ANODIZED |
| <p>Notes:</p> <ul style="list-style-type: none"> • Dimension A and B refer to component size. • Dimension C is the heat sink height from the bottom of the base to the top of the fin field. • ATS-59001-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10. • Thermal performance data are provided for reference only. Actual performance may vary by application. • ATS reserves the right to update or change its products without notice to improve the design or performance. • ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. • Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT170 • Contact ATS to learn about custom options available. | | | | | | |

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

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